PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT2688122

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HSIAO YUN LO	01/09/2014
LIN-CHIH HUANG	01/09/2014
TASI-JUNG WU	01/09/2014
HSIN-YU CHEN	01/09/2014
YUNG-CHI LIN	01/09/2014
KU-FENG YANG	01/14/2014
TSANG-JIUH WU	01/09/2014
WEN-CHIH CHIOU	01/09/2014

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77 R.O.C.

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14158364

CORRESPONDENCE DATA

Fax Number: (972)732-9218
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Correspondent Name: SLATER & MATSIL, L.L.P.
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Address Line 4:	DALLAS, TEXAS 75252
ATTORNEY DOCKET NUMBER:	TSM13-1604
NAME OF SUBMITTER:	LATOYA JENKINS
Signature:	/Latoya Jenkins/
Date:	01/17/2014

Total Attachments: 2
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ATTORNEY DOCKET NO.
TSM13-1604

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, Hsin-Chu 300-77, Taiwan, R.O.C., is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	***Interconnect Structure and Method of Forming Same***			
SIGNATURE OF INVENTOR AND NAME	Hsiao Yun Lo	Lin-Chih Huang	Tasi-Jung Wu	Hsin-Yu Chen
DATE	2014.01.09	20140109	2014.01.09	2014.1.9
RESIDENCE	Hsin-Chu, Taiwan	Wuri Township, Taiwan	Hsin-Chu, Taiwan	Taipei City, Taiwan

PATENT
REEL: 031998 FRAME: 0546

ATTORNEY DOCKET NO.
TSM13-1604

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. ("Assignee"), a corporation organized and existing under the laws of , with its principal office at No. 8, Li-Hsin Rd. 6 Science-Based Industrial Park, is desirous of acquiring my entire right, title and interest in and to said invention, and to said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to said Assignee, its successors and assigns, my entire right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all future non-provisional applications including divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to said Assignee, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to Assignee, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said Assignee, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said Assignee, its legal representatives, successors, or assigns, will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said Assignee, its legal representatives, successors, and assigns, to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	*Interconnect Structure and Method of Forming Same*			
SIGNATURE OF INVENTOR AND NAME	Yung-Chi Lin (signature) Yung-Chi Lin	Ku-Feng Yang (signature) Ku-Feng Yang	Tsang-Jiuh Wu (signature) Tsang-Jiuh Wu	Wen-Chih Chiou (signature) Wen-Chih Chiou
DATE	1/9 '14	2014 01.14	1/9 '14	1/9 '14
RESIDENCE	Su-Lin City, Taiwan	Dali City, Taiwan	Hsin-Chu, Taiwan	Zhunan Township Taiwan

PATENT
RECORDED: 01/17/2014 REEL: 031998 FRAME: 0547